

PRINTED WIRING BOARD MANUFACTURING METHOD
AND PRINTED WIRING BOARD

Abstract

A printed wiring board having a through hole conductor formed on the surface of a through hole formed in a copper-clad laminate board, and on the surface of the copper-clad laminate board 1 in the vicinity of an opening of the through hole. The through hole conductor is filled with a positive photosensitive resin. A capped conductor is formed on the positive photosensitive resin and is coupled to the through hole conductor. Further, a circuit pattern is formed on the surface of the copper-clad laminate board. An insulating layer is formed on the surface of the copper-clad laminate board, capped conductor, and the circuit pattern, and formed with a via hole extending from the surface of the insulating layer to the capped conductor. A via conductor is formed inside the via hole and on the surface of the insulating layer in the vicinity of an opening of the via hole.